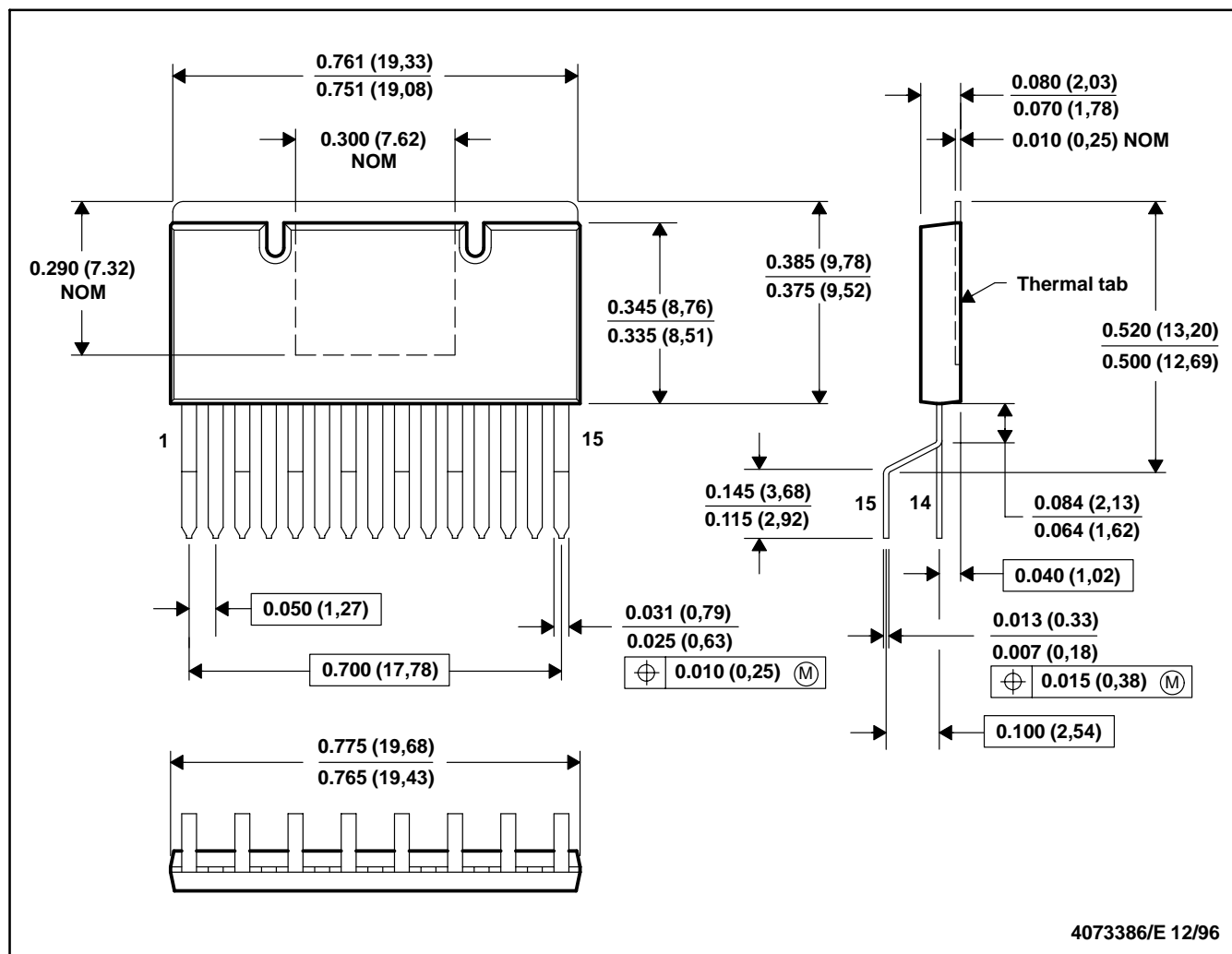


KTD (R-PSFM-T15)

PowerFLEX™ PLASTIC FLANGE-MOUNT PACKAGE



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Dimensions do not include mold protrusions (not to exceed 0.006 (0,15)).

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